Renesas RX Family

EK-RX74M Example Project Bundle

Introduction

This EK-RX74M Example Project Bundle introduces practical example projects for the EK-RX74M Kit. The Example Projects contained within the bundle show how to write code for the various Renesas Flexible Software Package (FSP) modules supported by the EK-RX74M kit.

Flexible Software Package is an optimized software package designed to provide easy to use, scalable, high-quality software for embedded system design. The primary goal is to provide lightweight, efficient drivers that meet common use cases in embedded systems. FSP code quality is enforced by peer reviews, automated requirements-based testing, and automated static analysis. FSP provides uniform and intuitive APIs that are well documented. Each module is supported with detailed user documentation including example code. FSP modules can be used on any MCU in the RX family, provided the MCU has any peripherals required by the module. FSP modules can be configured at build-time to optimize the size of the module for the feature set required by the application.

Supported Kit

EK-RX74M

Supported FSP Version

FSP v1.0.0

Supported Toolchains

For the latest version of each Integrated Development Environment (IDE) and toolchain listed below, please refer to the FSP release notes

- e² studio with GCC Compiler for RX (GCC-RX) or Renesas CC-RX Compiler (CC-RX)

1. Using the Example Projects

To use EK-RX74M Example Projects, follow the steps mentioned in the following document:

- Example Project Usage Guide
  https://github.com/renesas/rx-fsp-examples/blob/main/example_projects/Example_Project_Usage_Guide.pdf

Users who are new to the FSP are recommended to refer to the section **Starting Development** > **Tutorial: Your First RX MCU Project – Blinky** in the RX FSP Documentation prior to attempting to program or debug an example project.

2. List of Example Projects Supported on Different Toolchains in the Bundle

The following table lists example projects supported by each IDE. These are ready to import using the import process for each IDE.

Note:

1. Additional example projects other than those mentioned above, may be available in the example project repository. However, they are supported with older version of FSP. Please refer the example_projects/version_info_table.md file in the repository to identify the appropriate FSP version for the example project of interest.
2. All projects supported by e²studio /CC-RX are supported with e²studio /GCC-RX via port from CC-RX.

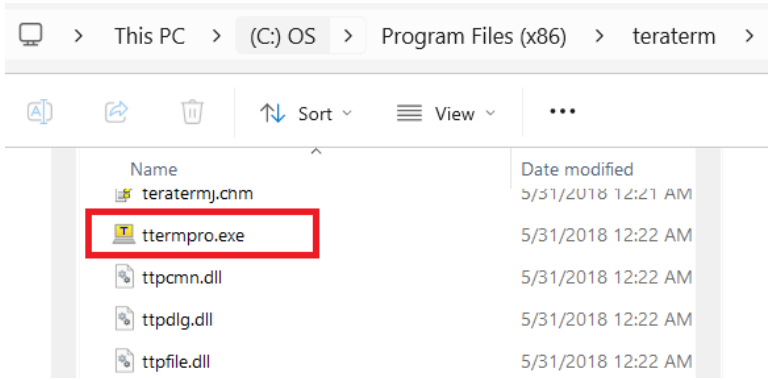
Table 1. IDE/Toolchain Support for the Example Projects

	IDE/Toolchain Support	
Example Project	**e2studio/GCC-RX**	**e2studio/CC-RX**
adc	Supported	Supported
adc_gpt_periodic_sampling	Supported	Supported
cac	Supported	Supported
can_fdg	Supported	Supported
clock_output	Supported	Supported
cmt	Supported	Supported
cmtw	Supported	Supported
crc	Supported	Supported
dac	Supported	Supported
dac_cmt_periodic_signal_generator	Supported	Supported
dmac	Supported	Supported
doc	Supported	Supported
dsmif	Supported	Supported
dtc	Supported	Supported
elc	Supported	Supported
ethernet	Supported	Supported
exdmac	Supported	Supported
freertos	Supported	Supported
freertos_tcp_dualport	Supported	Supported
gpt	Supported	Supported
gpt_input_capture	Supported	Supported
i3c_master	Supported	Supported
i3c_slave	Supported	Supported
icu	Supported	Supported
iic_master	Supported	Supported
iic_slave	Supported	Supported
iwdt	Supported	Supported
lpm	Supported	Supported
mram	Supported	Supported
octa_ram	Supported	Supported
pcif	Supported	Supported
poeg	Supported	Supported
pvd	Supported	Supported
rsip	Supported	Supported
rtc	Supported	Supported
sci_i2c	Supported	Supported

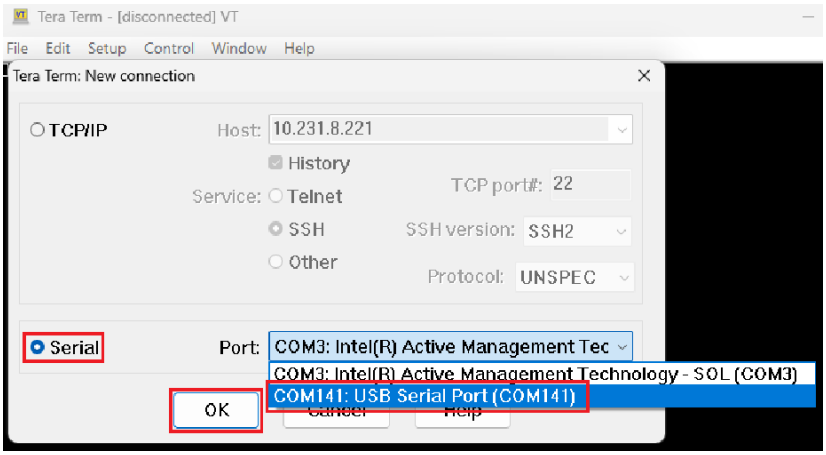
	IDE/Toolchain Support	
Example Project	**e2studio/GCC-RX**	**e2studio/CC-RX**
sci_spi	Supported	Supported
sci_uart	Supported	Supported
sdhi	Supported	Supported
spi	Supported	Supported
ssi	Supported	Supported
tmr	Supported	Supported
usb_composite_phid_phid	Supported	Supported
usb_hcdc	Supported	Supported
usb_hhid	Supported	Supported
usb_hmsc	Supported	Supported
usb_hmsc_baremetal	Supported	Supported
usb_hvnd	Supported	Supported
usb_multiport	Supported	Supported
usb_pcdc	Supported	Supported
usb_pcdc_with_freertos	Supported	Supported
usb_phid	Supported	Supported
usb_pvnd	Supported	Supported
wdt	Supported	Supported
xspi_controller	Supported	Supported
_quickstart		Supported

3. Running the Project

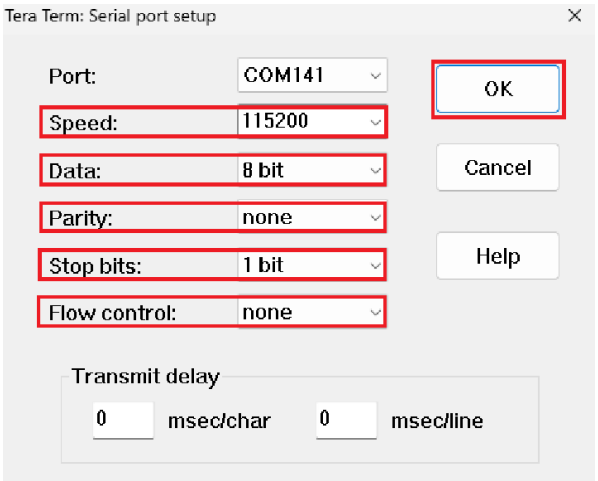
1. Open **Tera Term** by double-clicking `ttermpro.exe` in the Tera Term installation folder.



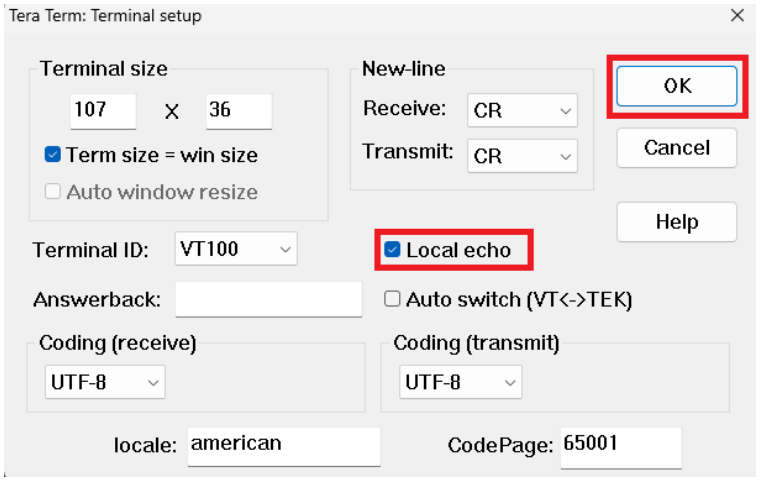
2. In the **New connection** dialog box, select **Serial**. From the Port drop-down list, select the COM port assigned to the RX board kit, and then select **OK**.



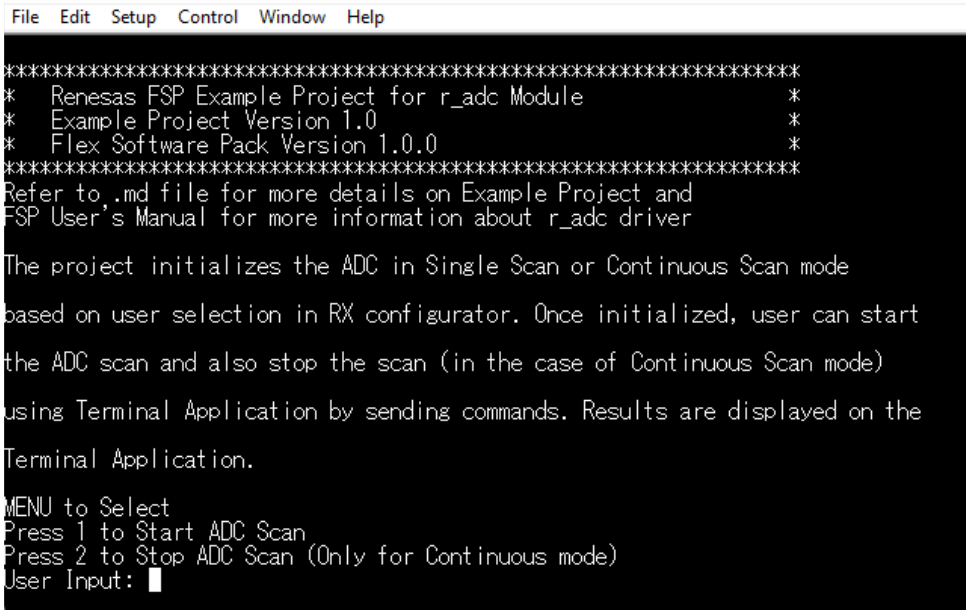
3. In **Tera Term**, select `Setup > Serial port…` Verify the serial port settings match the values below, and then select **OK**.
   Note: Use the following serial port settings:
   - Baud rate: 115200 bps
   - Data length: 8 bits
   - Parity: None
   - Stop bit: 1 bit
   - Flow control: None



4. Select `Setup > Terminal...` and enable **Local echo** when typed input must be displayed.



5. To use the **RESET** push button, set **SW6-1** to **ON**, and then press the **RESET** push button to run the application. The application output is displayed in the **Tera Term** terminal.



To continue programming the application using the E2 On-board, set **SW6-1** to **OFF**.

Website and Support

Visit the following URLs to learn about key elements of the RX family, download components and related documentation, and get support.

RX Product Information	renesas.com/rx
RX Product Support Forum	renesas.com/rx/forum
RX Flexible Software Package	renesas.com/rx-fsp
Renesas Support	renesas.com/support

Revision History

		Description	
Rev.	**Date**	**Page**	**Summary**
1.00	Oct.12.26	—	First release document.
1.01	Oct.28.26	1, 2, 5, 6	Correct links and improve content.

General Precautions in the Handling of Microprocessing Unit and Microcontroller Unit Products

The following usage notes are applicable to all Microprocessing unit and Microcontroller unit products from Renesas. For detailed usage notes on the products covered by this document, refer to the relevant sections of the document as well as any technical updates that have been issued for the products.

1. Precaution against Electrostatic Discharge (ESD)

   A strong electrical field, when exposed to a CMOS device, can cause destruction of the gate oxide and ultimately degrade the device operation. Steps must be taken to stop the generation of static electricity as much as possible, and quickly dissipate it when it occurs. Environmental control must be adequate. When it is dry, a humidifier should be used. This is recommended to avoid using insulators that can easily build up static electricity. Semiconductor devices must be stored and transported in an anti-static container, static shielding bag or conductive material. All test and measurement tools including work benches and floors must be grounded. The operator must also be grounded using a wrist strap. Semiconductor devices must not be touched with bare hands. Similar precautions must be taken for printed circuit boards with mounted semiconductor devices.

2. Processing at power-on

   The state of the product is undefined at the time when power is supplied. The states of internal circuits in the LSI are indeterminate and the states of register settings and pins are undefined at the time when power is supplied. In a finished product where the reset signal is applied to the external reset pin, the states of pins are not guaranteed from the time when power is supplied until the reset process is completed. In a similar way, the states of pins in a product that is reset by an on-chip power-on reset function are not guaranteed from the time when power is supplied until the power reaches the level at which resetting is specified.

3. Input of signal during power-off state

   Do not input signals or an I/O pull-up power supply while the device is powered off. The current injection that results from input of such a signal or I/O pull-up power supply may cause malfunction and the abnormal current that passes in the device at this time may cause degradation of internal elements. Follow the guideline for input signal during power-off state as described in your product documentation.

4. Handling of unused pins

   Handle unused pins in accordance with the directions given under handling of unused pins in the manual. The input pins of CMOS products are generally in the high-impedance state. In operation with an unused pin in the open-circuit state, extra electromagnetic noise is induced in the vicinity of the LSI, an associated shoot-through current flows internally, and malfunctions occur due to the false recognition of the pin state as an input signal become possible.

5. Clock signals

   After applying a reset, only release the reset line after the operating clock signal becomes stable. When switching the clock signal during program execution, wait until the target clock signal is stabilized. When the clock signal is generated with an external resonator or from an external oscillator during a reset, ensure that the reset line is only released after full stabilization of the clock signal. Additionally, when switching to a clock signal produced with an external resonator or by an external oscillator while program execution is in progress, wait until the target clock signal is stable.

6. Voltage application waveform at input pin

   Waveform distortion due to input noise or a reflected wave may cause malfunction. If the input of the CMOS device stays in the area between V_{IL} (Max.) and V_{IH} (Min.) due to noise, for example, the device may malfunction. Take care to prevent chattering noise from entering the device when the input level is fixed, and also in the transition period when the input level passes through the area between V_{IL} (Max.) and V_{IH} (Min.).

7. Prohibition of access to reserved addresses

   Access to reserved addresses is prohibited. The reserved addresses are provided for possible future expansion of functions. Do not access these addresses as the correct operation of the LSI is not guaranteed.

8. Differences between products

   Before changing from one product to another, for example to a product with a different part number, confirm that the change will not lead to problems. The characteristics of a microprocessing unit or microcontroller unit products in the same group but having a different part number might differ in terms of internal memory capacity, layout pattern, and other factors, which can affect the ranges of electrical characteristics, such as characteristic values, operating margins, immunity to noise, and amount of radiated noise. When changing to a product with a different part number, implement a system-evaluation test for the given product.

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